

Product Summary (@ T_A = +25°C)

V _{RRM} (V)	I _O (A)	V _F Max (V)	I _R Max (μA)
1200	1	2.0	5

Description

The US1NWF is a rectifier packaged in the SOD123F package and is suited as a boost diode in power factor correction circuitry. For use in secondary rectification and freewheeling for ultra-fast switching speed AC-AC and DC-DC converters in high-temperature conditions for consumer applications.

Applications

- Flat Panel Display
- Switching Power Supplies/Chargers
- LED Lighting
- Freewheeling Diode

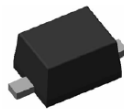
Features and Benefits

- Low Profile, Small Form Factor Package
- Low Leakage Current
- Glass Passivate Die Construction
- Ultrafast Recovery Times for High Efficiency
- Low Forward Voltage, Low Power Loss
- Lead-Free Finish & RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)**
- Qualified to AEC-Q101 Standards for High Reliability**

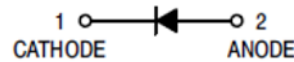
Mechanical Data

- Case: SOD123F
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 
- Polarity: Cathode Band
- Weight: 0.016 grams (Approximate)

SOD123F



Top View



Schematic View

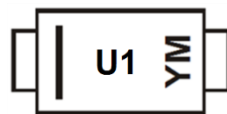
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
US1NWF-7	AEC-Q101	SOD123F	3,000/Tape & Reel

- Notes:
- EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 - See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 - Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 - For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information

SOD123F



U1 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: E = 2017)
 M = Month (ex: 9 = September)

Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022
Code	C	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	1200	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Average Rectified Output Current	I _O	1	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case (Note 6)	R _{θJC}	33	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	100	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	82	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	1200	—	—	V	I _R = 10μA
Forward Voltage	V _F	—	1.3 1.4 1.5	1.7 1.9 2.0	V	I _F = 0.5A, T _J = +25°C I _F = 0.8A, T _J = +25°C I _F = 1A, T _J = +25°C
Reverse Leakage Current (Note 7)	I _R	—	0.5 10	5 100	μA	V _R = 1200V, T _J = +25°C V _R = 1200V, T _J = +125°C
Reverse Recovery Time	t _{RR}	—	70	80	ns	I _F = 0.5A, I _R = 1.0A, I _{RR} = 0.25A
Total Capacitance	C _T	—	5	—	pF	V _R = 4V, f=1MHz

- Notes:
- Device mounted on FR-4 substrate, 25.4*25.4mm, 2oz, single-sided, PC boards with 2.1*2.1mm copper.
 - Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pad.
 - Short duration pulse test used to minimize self-heating effect.

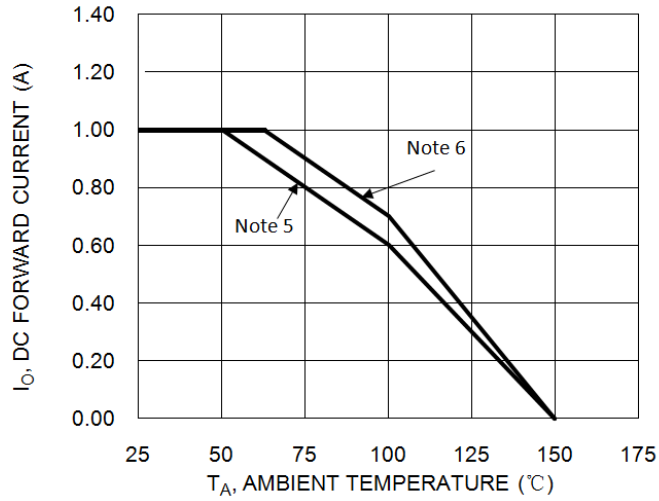


Figure 1. DC Forward Current Derating

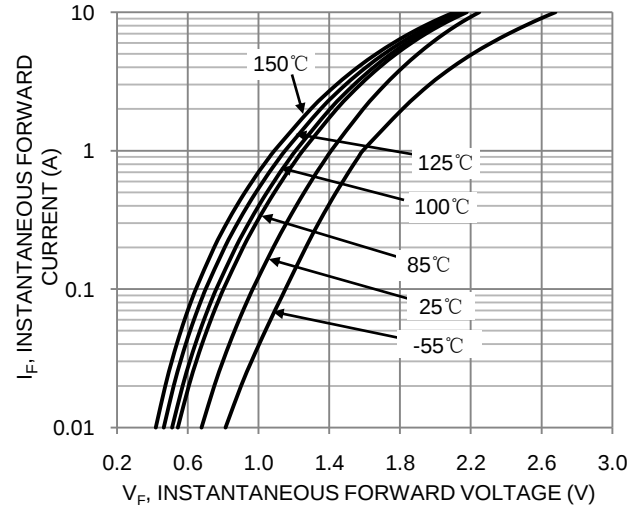


Figure 2. Typical Forward Characteristics

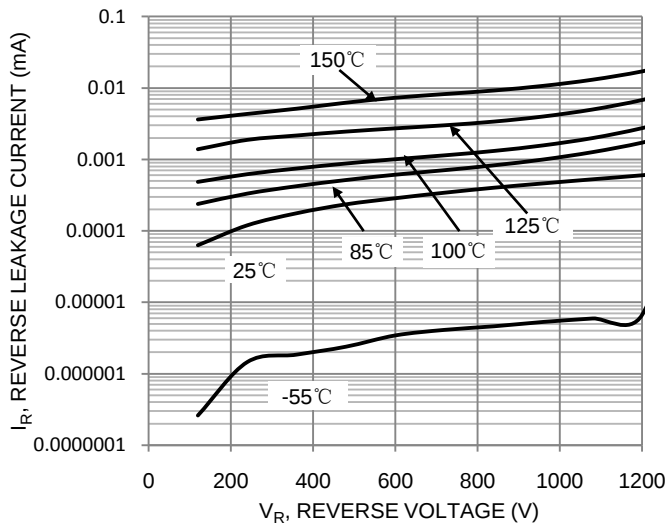


Figure 3. Typical Reverse Characteristics

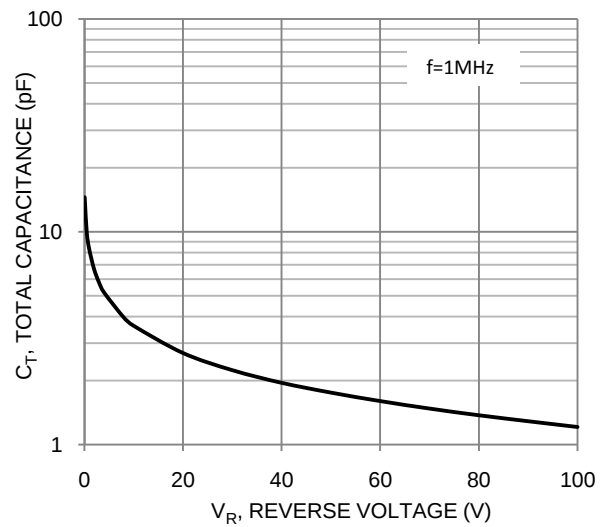


Figure 4. Typical Forward Characteristics

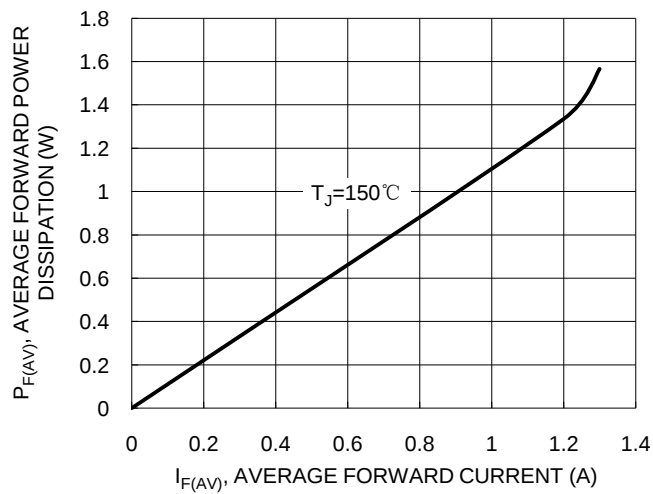
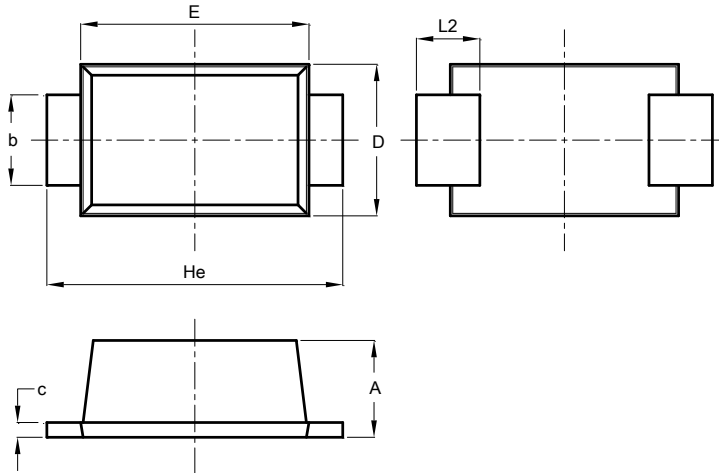


Figure 5. Forward Power Dissipation

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F

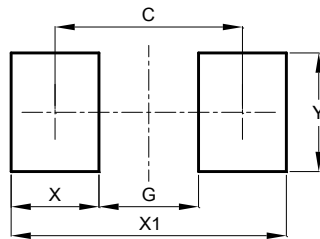


SOD123F			
Dim	Min	Max	Typ
A	0.81	1.15	-
b	0.80	1.05	-
c	0.05	0.30	-
D	1.70	1.90	1.80
E	2.60	2.80	2.70
He	3.30	3.70	3.50
L2	0.35	0.85	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOD123F



Dimensions	Value (in mm)
C	2.86
G	1.52
X	1.34
X1	4.20
Y	1.80

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